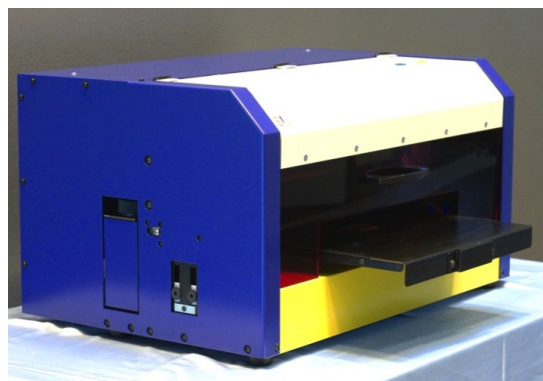


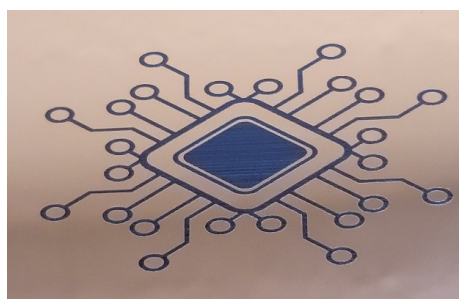
SMART Printer

UV Resin Printing & Curing, All in One!

- Minimum Line Width: approx. 100 μ m
- Printing Resolution: 1440 \times 1440 dpi equivalent
- A4 Printing Speed: approx. 240 sec
(high-speed mode)
- Ink Replenishment: only 1 minute
- Perfect for: small-lot, multi-variety production



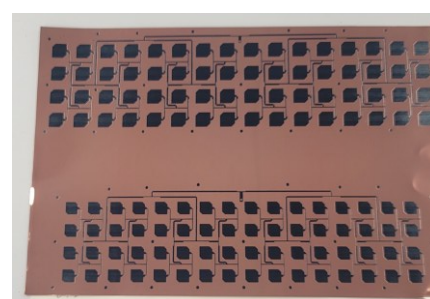
Example printing



Circuit Patterning



Insulating Switch Contacts



Antenna Patterning

Example Applications

- ◆Mask printing on glass substrates and optical components
- ◆Insulation pattern printing on electrical components.
- ◆Etch-mask printing on copper-laminated substrates and flexible copper-films.
A circuit substrate can be created by etching after printing.

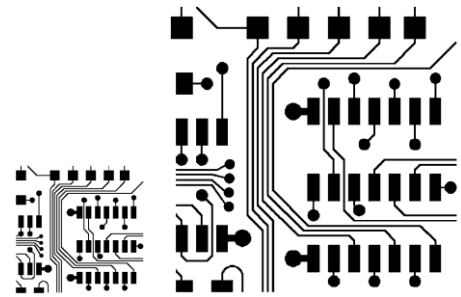
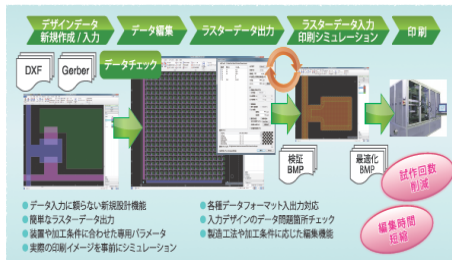
Specification

Specification	SMART printer (SMP-3021)
Print mechanism	Piezo inkjet (Minimum line width = 100 μ m, Depending on conditions)
Print data format	Binary BMP data
Available substrate size	300 mm (W) x 210 mm (D) x 1.0-1.6mm (H) *Compatible with Thicknesses up to 30 mm (using optional spacer)
Print speed	100 mm/sec, 250 mm/sec (selectable)
Body size	Approx. 600 mm (W) x 350 mm (D) x 350 mm (H)
Power consumption	AC100~250V Power Consumption< 100 W
Option	DMF Inkjet (printing data creation software) , Vacuum stage

Printing process

Step 1. Prepare print data (BMP image)

Convert DXF, Gerber, PDF data to BMP data using editing software (DFM Inkjet, etc.).



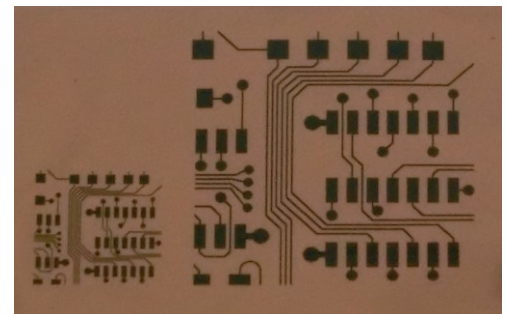
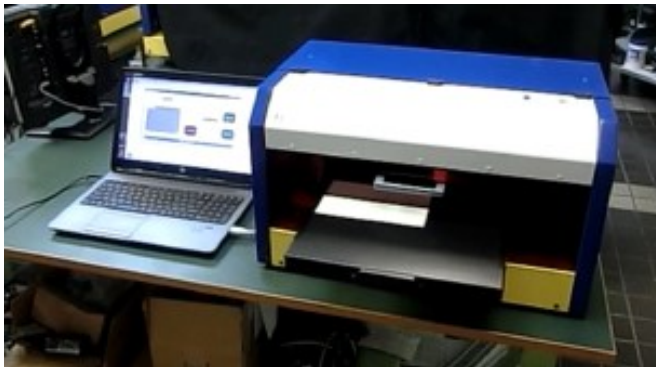
Binary BMP data

Step 2. Print

Operate the printer from PC

Just set the substrate and press the print button.

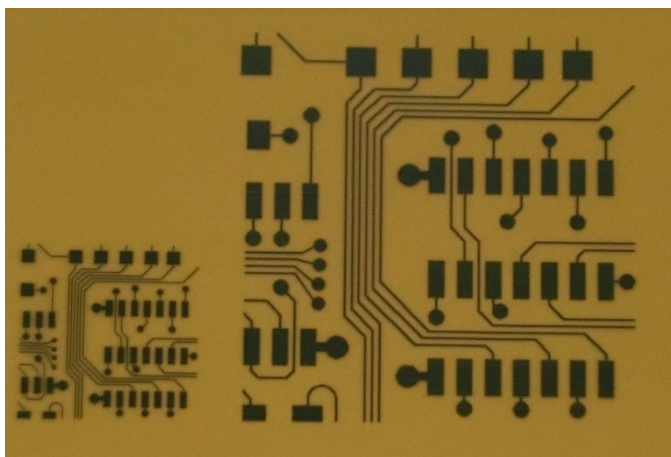
※When printing resist material, UV irradiation is performed inside the printer.



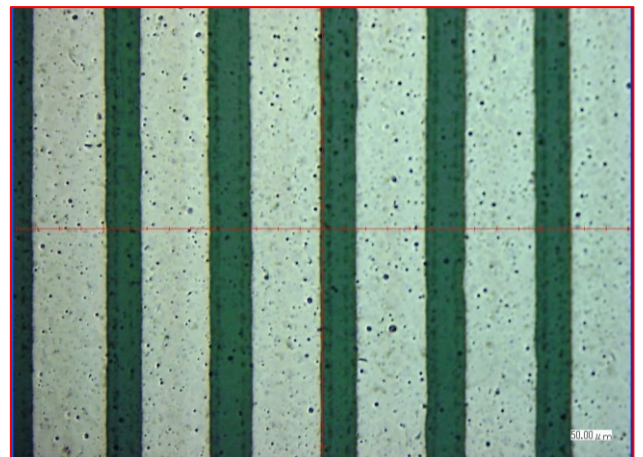
After print

Step 3. Etching

Resist mask fabrication (Etching mask fabrication)



Step 4. Remove resist material



Case)

Substrate: Cu-coated PI

Line width: 200 μm

Space: 50 μm